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(71) Applicant: **CHOO, WEI FERN** [SG/SG]; 6A Boscombe Road, Singapore 439741 (SG).

(72) Inventor: **CHOO, Wei Fern**; 6A Boscombe Road, Singapore 439741 (SG).

(74) Agent: **YUSARN AUDREY**; 24 Raffles Place, #27-01 Clifford Centre, Singapore 048621 (SG).

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(54) Title: SYSTEM AND METHOD OF MAKING COMPOSITE BOARDS

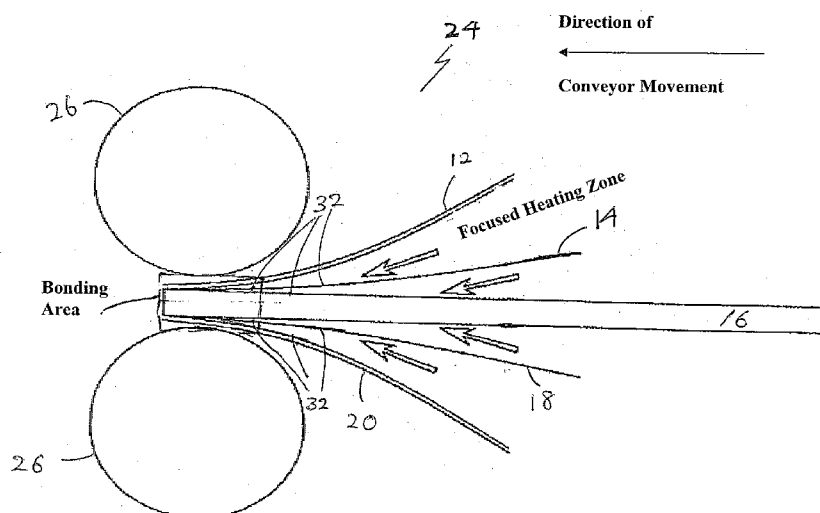


Fig. 2A

(57) Abstract: A method of bonding a plurality of layers for producing a laminated composite board comprising the steps of applying heat activated adhesive on a bonding surface of each layer from the plurality of layers which is to be bonded, and directing a localized heat source to the bonding surface and the applied heat activated adhesive as the composite board is being laminated, is disclosed. FIG. 2A